MB1M~MB10M

Rev.C Feb.-2015

蓝箭电子
BLUE ROCKET ELECTRONICS
DATA SHEET

描述 / Descriptions

0.8A 直插玻璃钝化整流桥，MBM 封装。
0.8A DIP Glass Passivated Bridge Rectifier, MBM package.

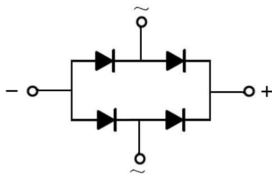
特征 / Features

玻璃钝化芯片，反向电压：100V~1000V，正向电流：0.8A，浪涌电流大。
Glass Passivated Chip Junction, Reverse Voltage:100to1000V, Forward Current：0.8 A, High Surge Current Capability.

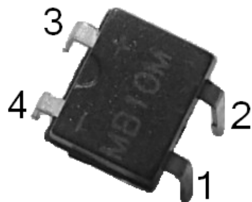
用途 / Applications

一般用途.
General purpose.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

印章代码 / Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25℃)

参数 Parameter	符号 Symbol	数值 Rating						单位 Unit
		MB1M	MB2M	MB4M	MB6M	MB8M	MB10M	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Currentat T_a = 50℃	I_o	0.8						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	30						A
Typical Junction Capacitance（Note1）	C_j	13						pF
Typical Thermal Resistance（Note2）	$R_{\theta JA}$	95						℃/W
Typical Thermal Resistance（Note2）	$R_{\theta JL}$	30						℃/W
Operating and Storage Temperature Range	T_j,T_{stg}	-55~+150						℃

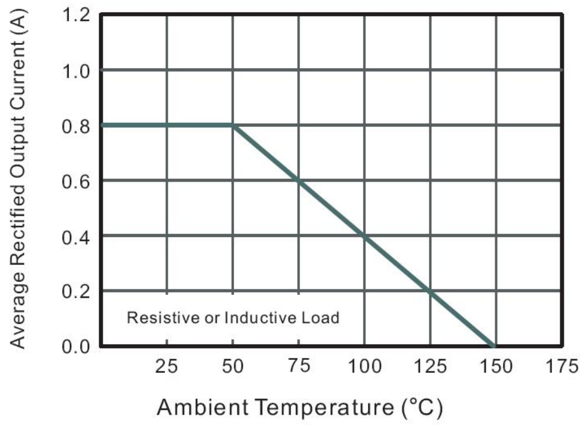
Note:

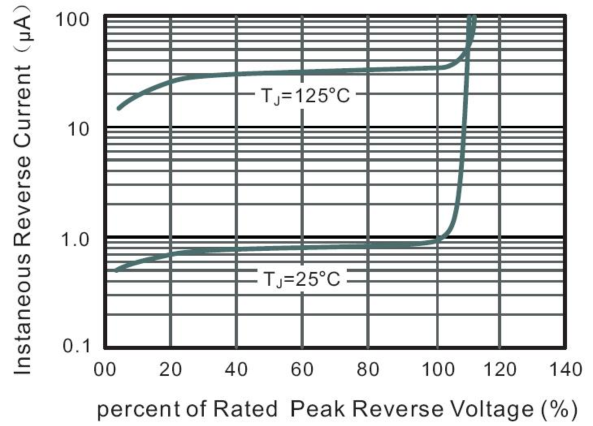
1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4×(5×5mm^2） copper pad..

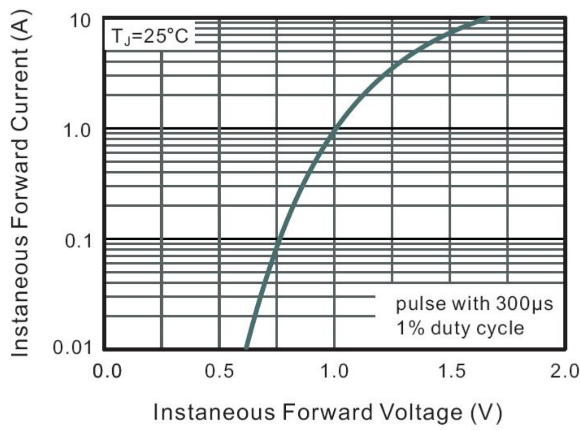
电性能参数 / Electrical Characteristics(Ta=25℃)

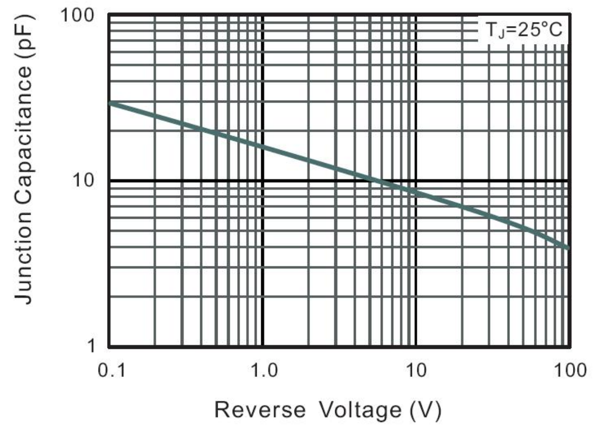
参数 Parameter	符号 Symbol	测试条件 Test condition	数值 Rating	单位 Unit
Maximum Forward Voltage	V_F	I_F=0.4A	1.0	V
		I_F=0.8A	1.1	
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	T_a=25℃ T_a=125℃	5.0 40	μA

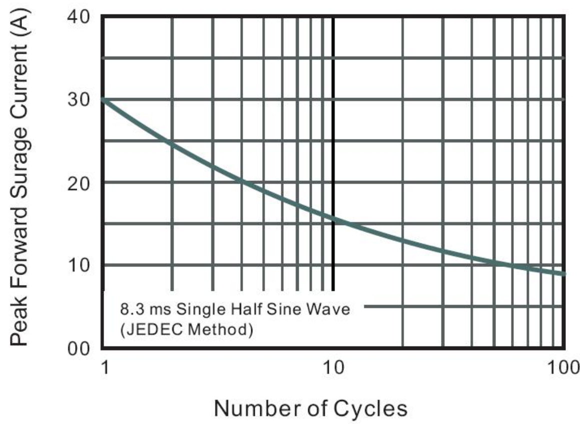
电参数曲线图 / Electrical Characteristic Curve





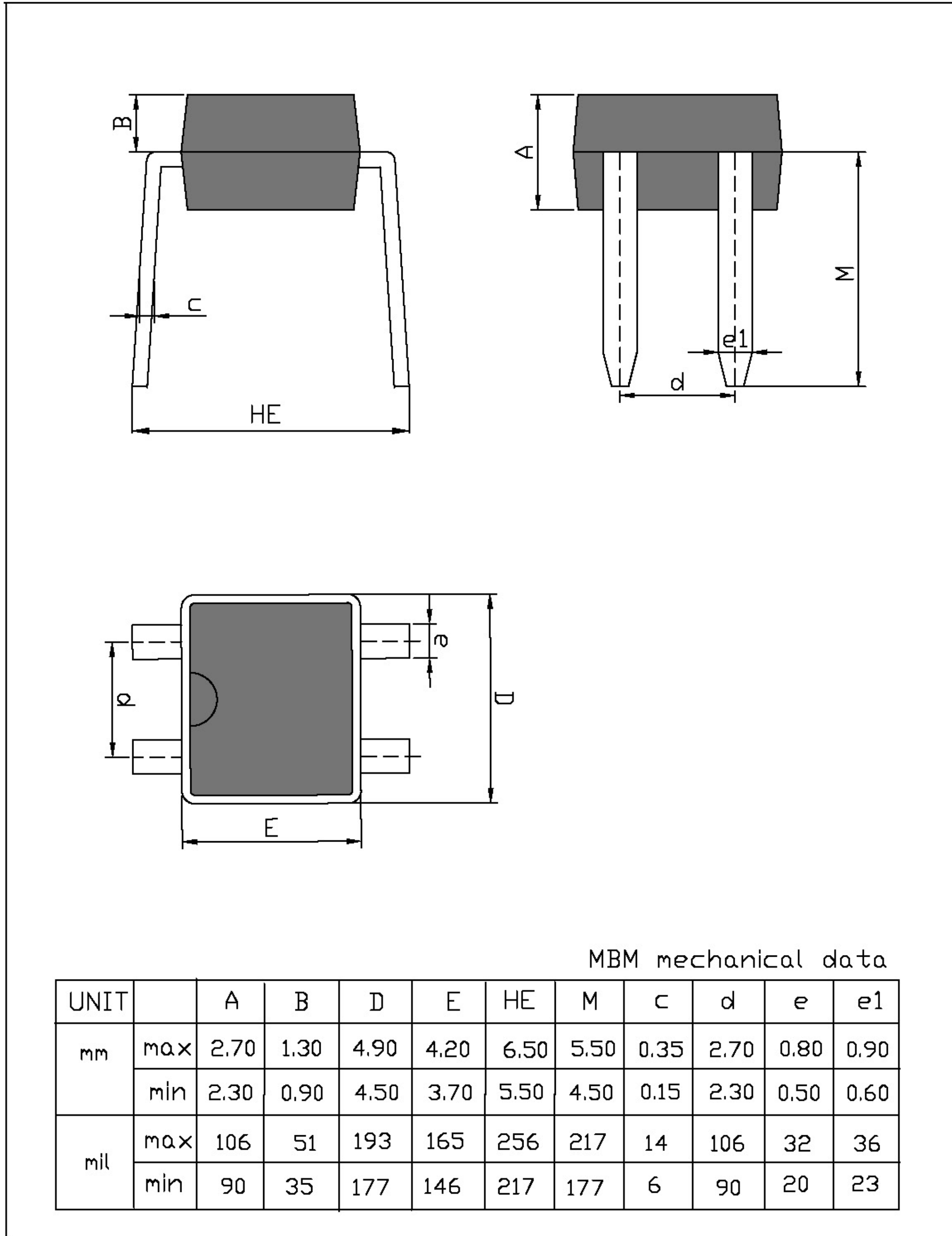






外形尺寸图 / Package Dimensions

MBM



MBM mechanical data

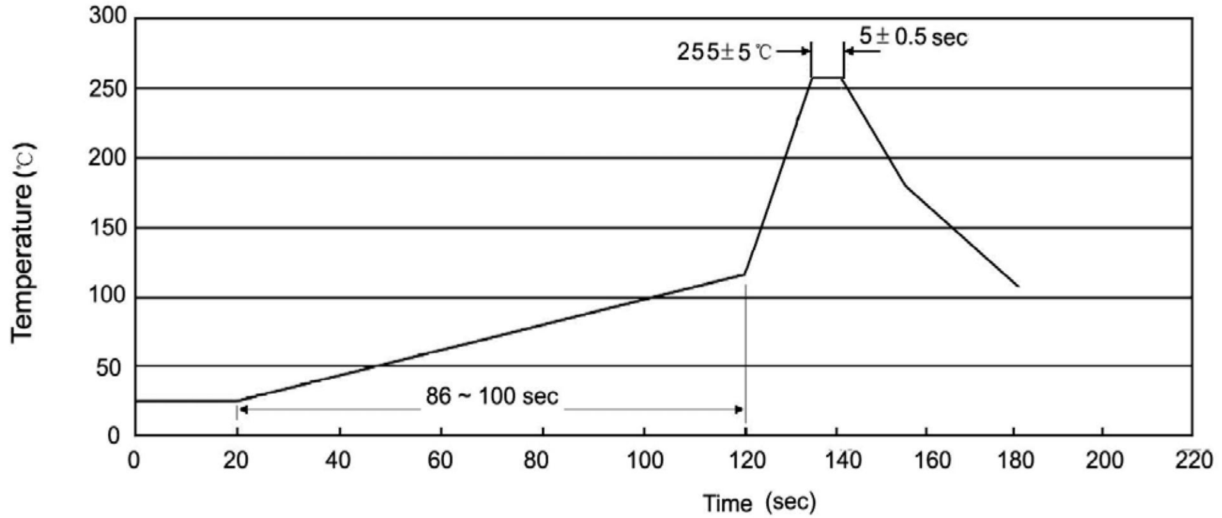
UNIT		A	B	D	E	HE	M	c	d	e	e1
mm	max	2.70	1.30	4.90	4.20	6.50	5.50	0.35	2.70	0.80	0.90
	min	2.30	0.90	4.50	3.70	5.50	4.50	0.15	2.30	0.50	0.60
mil	max	106	51	193	165	256	217	14	106	32	36
	min	90	35	177	146	217	177	6	90	20	23

印章说明 / Marking Instructions

Marking

Type number	Marking code
MB1M	MB1M
MB2M	MB2M
MB4M	MB4M
MB6M	MB6M
MB8M	MB8M
MB10M	MB10M

波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)



说明：

1、预热温度 25～150℃，时间 60～90sec;

2、峰值温度 255±5℃，时间持续为 5±0.5sec;

3、焊接制程冷却速度为 2～10℃/sec.

Note:

1.Preheating:25~150℃, Time:60~90sec.

2.Peak Temp.:255±5℃, Duration:5±0.5sec.

3. Cooling Speed: 2~10℃/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：270±5℃ 时间：10±1 sec.

Temp.:270±5℃ Time:10±1 sec

包装规格 / Packaging SPEC.

套管包装 / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
MBM	100	50	5000	4	20000			

使用说明 / Notices